

# Voltage Noise Induced DRAM Soft Error Reduction Technique for 3D CPUs

Tiantao Lu, Caleb Serafy, Zhiyuan Yang  
Advisor: Ankur Srivastava



INSTITUTE FOR SYSTEMS RESEARCH  
A. JAMES CLARK SCHOOL OF ENGINEERING

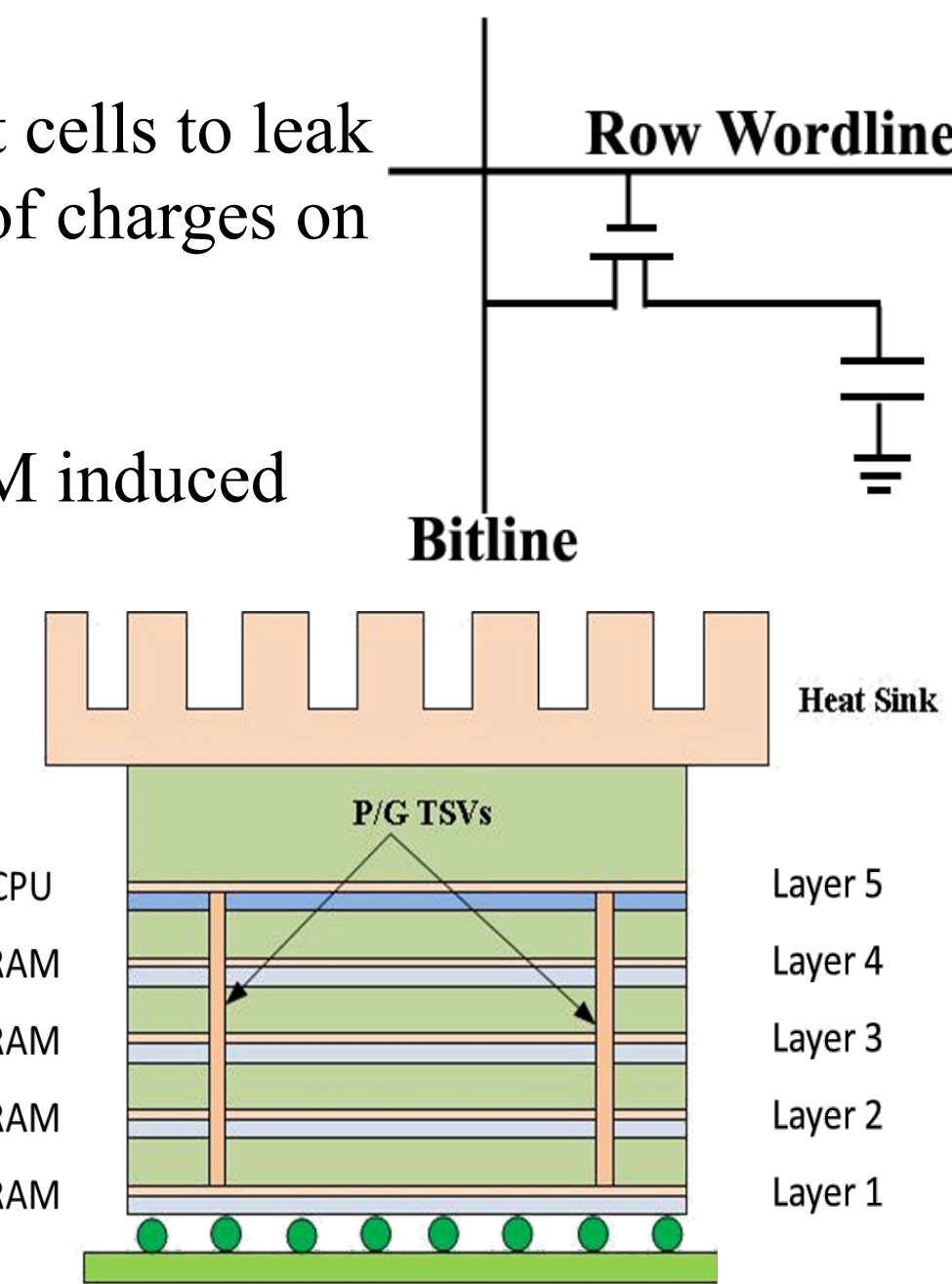
## Background

### Soft Error in DRAM

- Voltage noise on DRAM wordline causes DRAM bit cells to leak
- Bit flip occurs when the accumulation (or deletion) of charges on the capacitors exceeds the noise margin
- Hard to correct or even detect multi-bit soft errors
- Previous work mainly focuses on soft error in DRAM induced by external particles

### Soft Error in Stacked DRAM

- CPU and DRAM share the power delivery network
- More severe thermal and voltage noise problems
- Strong voltage noise coupling between CPU and DRAM



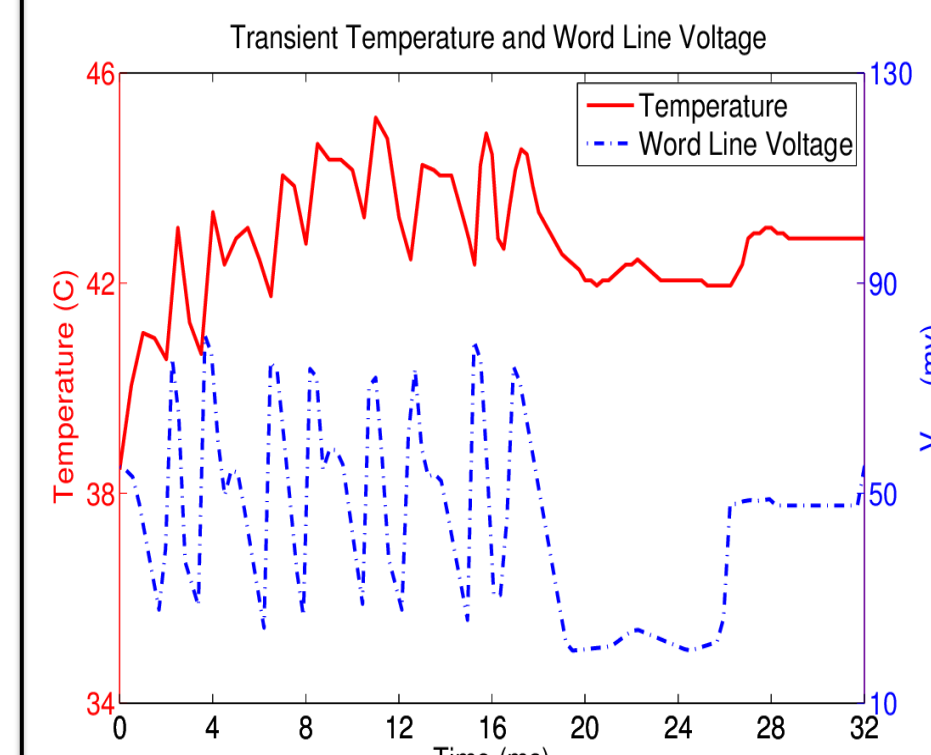
## Power and Thermal Analysis

### Power Delivery Analysis

- Strong coupling between DRAM and CPU
- Variance of bottom DRAM layer (DRAM layer 1) is smaller than that of CPU layer

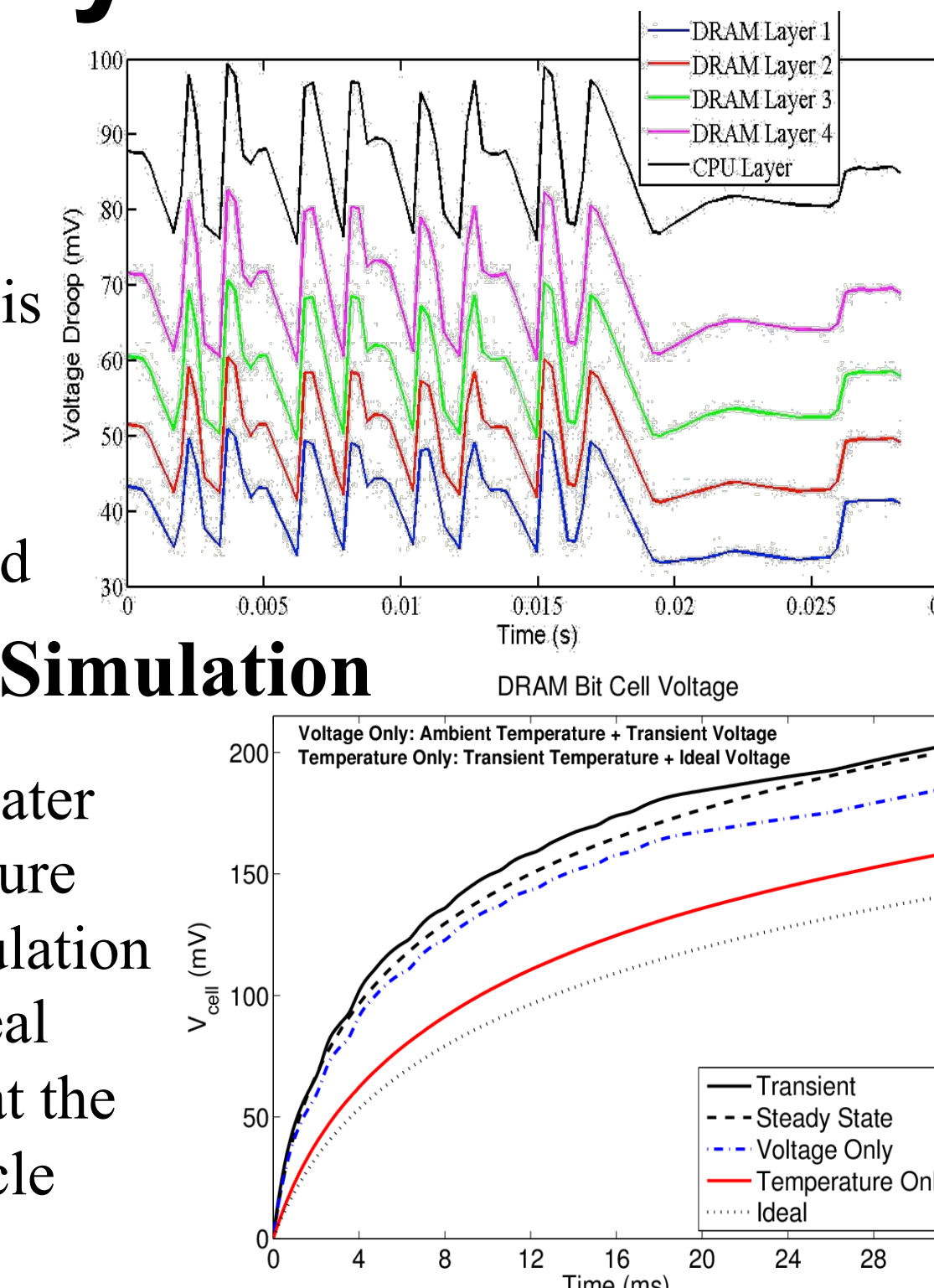
### Thermal Analysis

- Temperature and voltage noise are highly correlated



### DRAM SPICE Simulation

- Voltage noise has greater impact than temperature
- The steady state simulation converges with the real transient simulation at the end of the refresh cycle



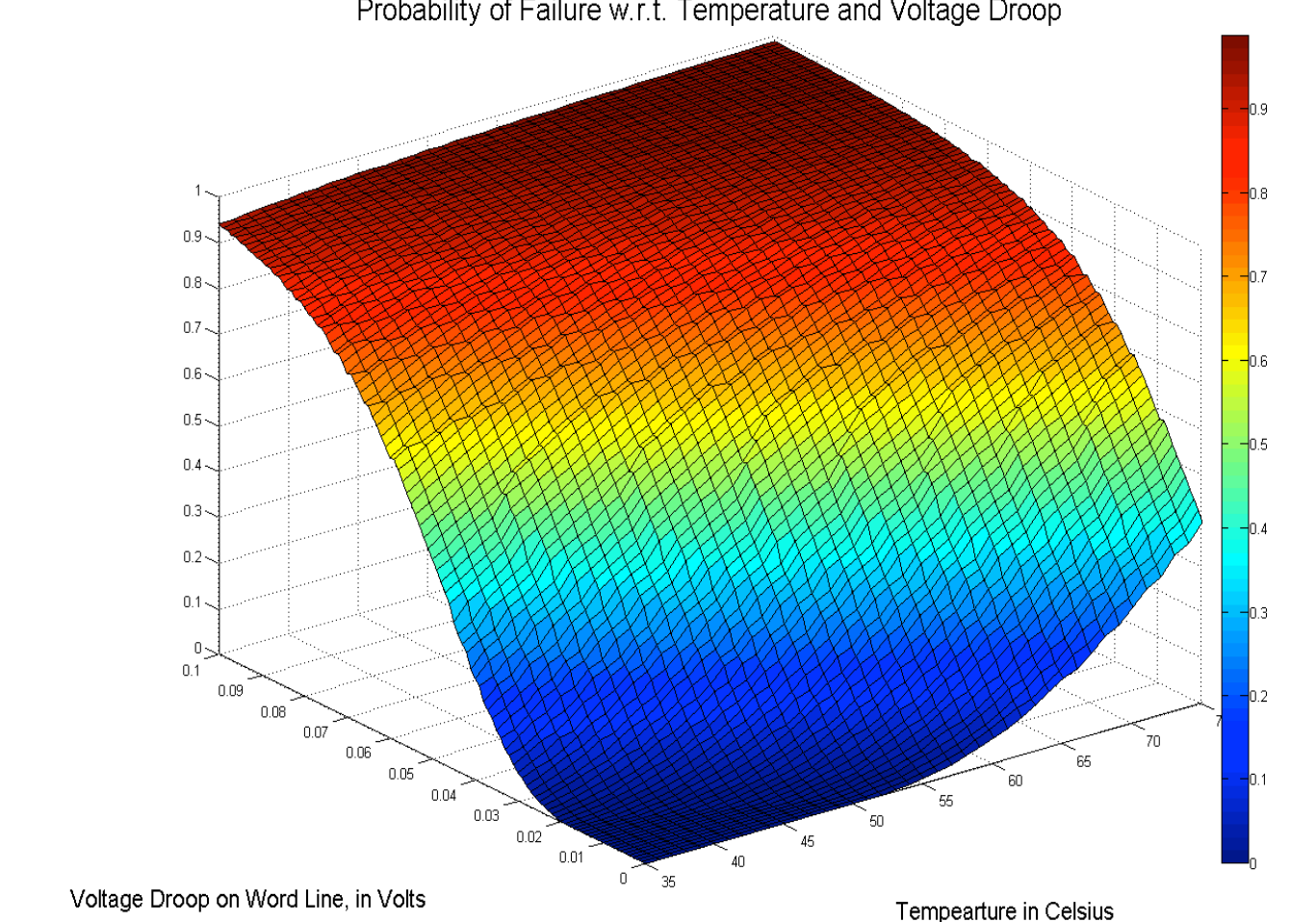
## Reliability Analysis

### Probability of Bit Error (POBE)

- DRAM bit cell's POF w.r.t. Temperature and wordline voltage
- Manufacturing randomness (oxide thickness) is considered
- Increasing voltage noise and temperature both increase  $P \downarrow BE$

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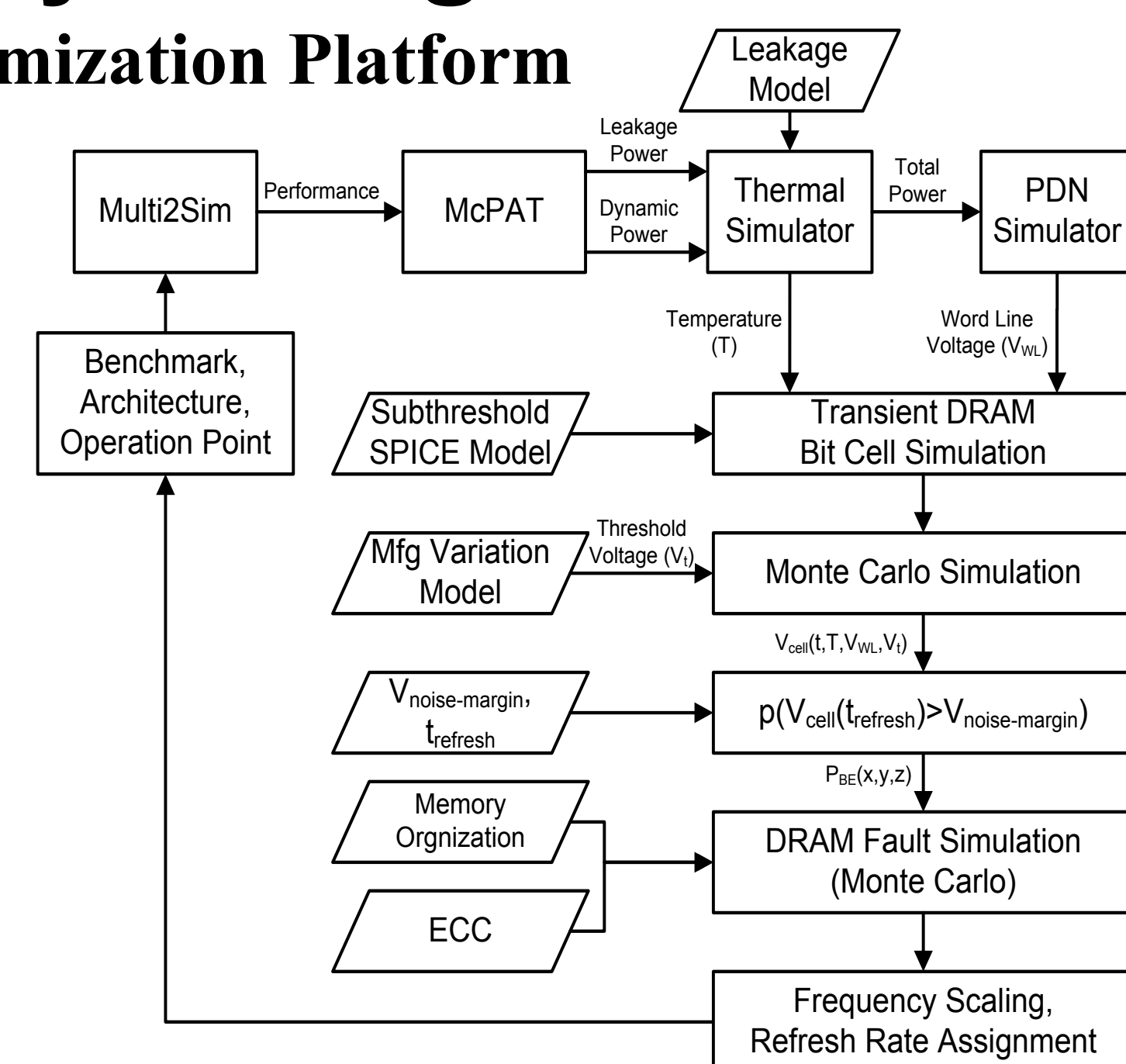
- Voltage noise has a more pronounced effect



## Dynamic Reliability Management

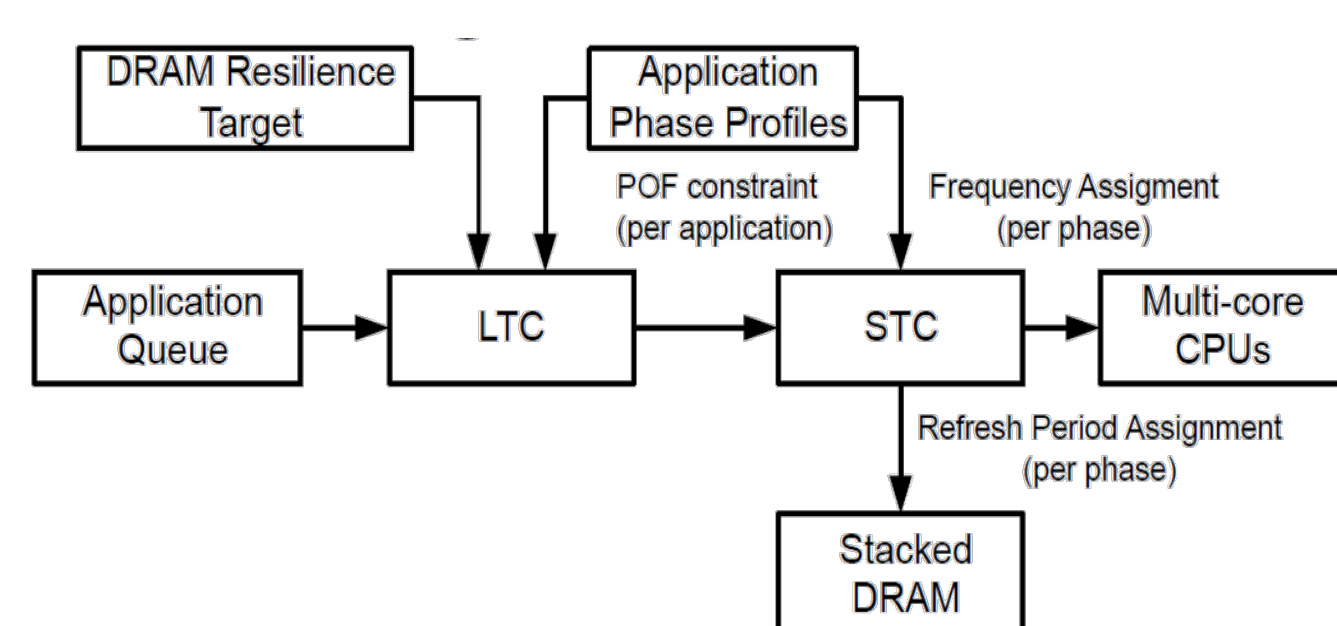
### Co-simulation and Co-optimization Platform

- Multi-dimensional problem: performance, power, thermal, DRAM resilience etc.
- Multi-scale problem: performance transient (cycle-accurate) vs. DRAM resilience (long-term)
- Statistical problem: process variation



### Dynamic Management

- Dynamic voltage and frequency scaling (DVFS)
- Dynamic refresh period adjustment



- Optimization Goal:** maximize the system performance
- Constraint:** DRAM resilience target (long-term probability of an uncorrectable memory error)

- LTC:** Long-term controller determines at which operating point each application should be run to minimize runtime while meeting the long-term DRAM resilience
- STC:** Short-term controller optimizes the runtime of each application by assigning an operating point to each phase of the application.
- Observation:** an application with high power (high performance) may require frequency to be reduced, whereas a lower power application puts less stress on the DRAM resiliency and can be configured with a longer refresh period and get a performance boost

## Simulation Results

### Settings

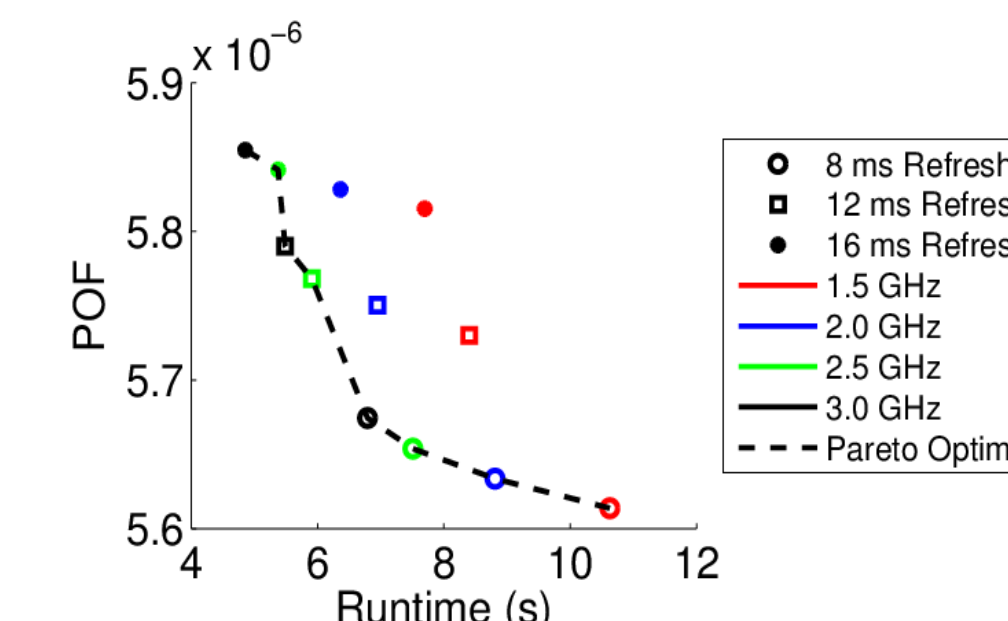
- DRAM noise margin: 10%  $V_{dd}$
- POF constraint: 0.3%
- LTC control window: 30 minutes
- Nominal case: 3GHz clock rate + 8ms refresh period
- Frequency selection: {3.0, 2.5, 2.0, 1.5} GHz
- Refresh period selection: {8, 12, 16, 32, 64} ms

	Optimal	Nominal
Probability of uncorrectable error	0.30%	0.23%
Throughput(jobs/sec)	0.29	0.23
Normalized Throughput	1.27	1.00

### Discussion

- Our controller improves performance in two ways
- Distribution of operating points

- The operating points that are not on the Pareto optimal from will never be chosen
- 32/64 ms refresh periods are never chosen due to fast bit flip

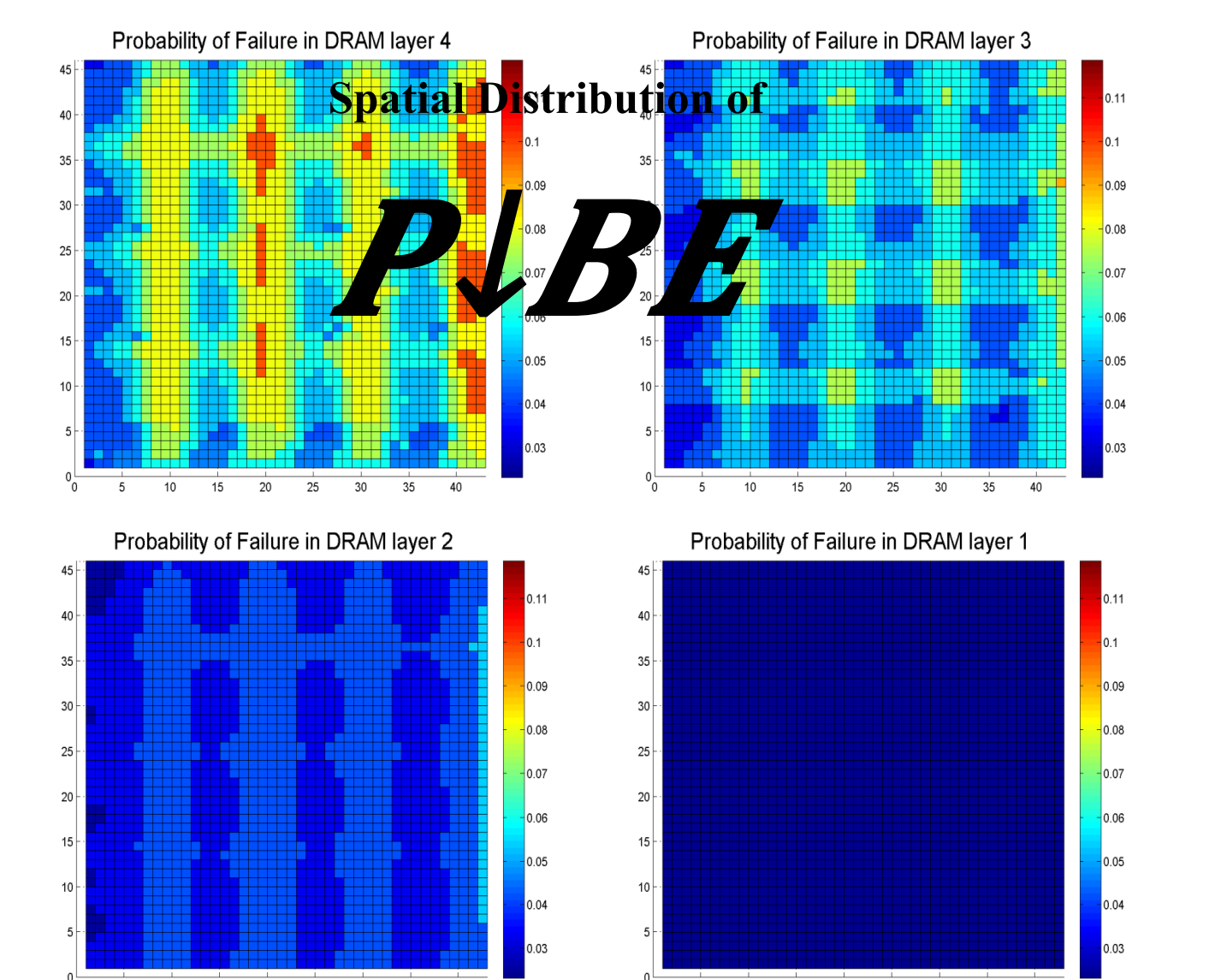
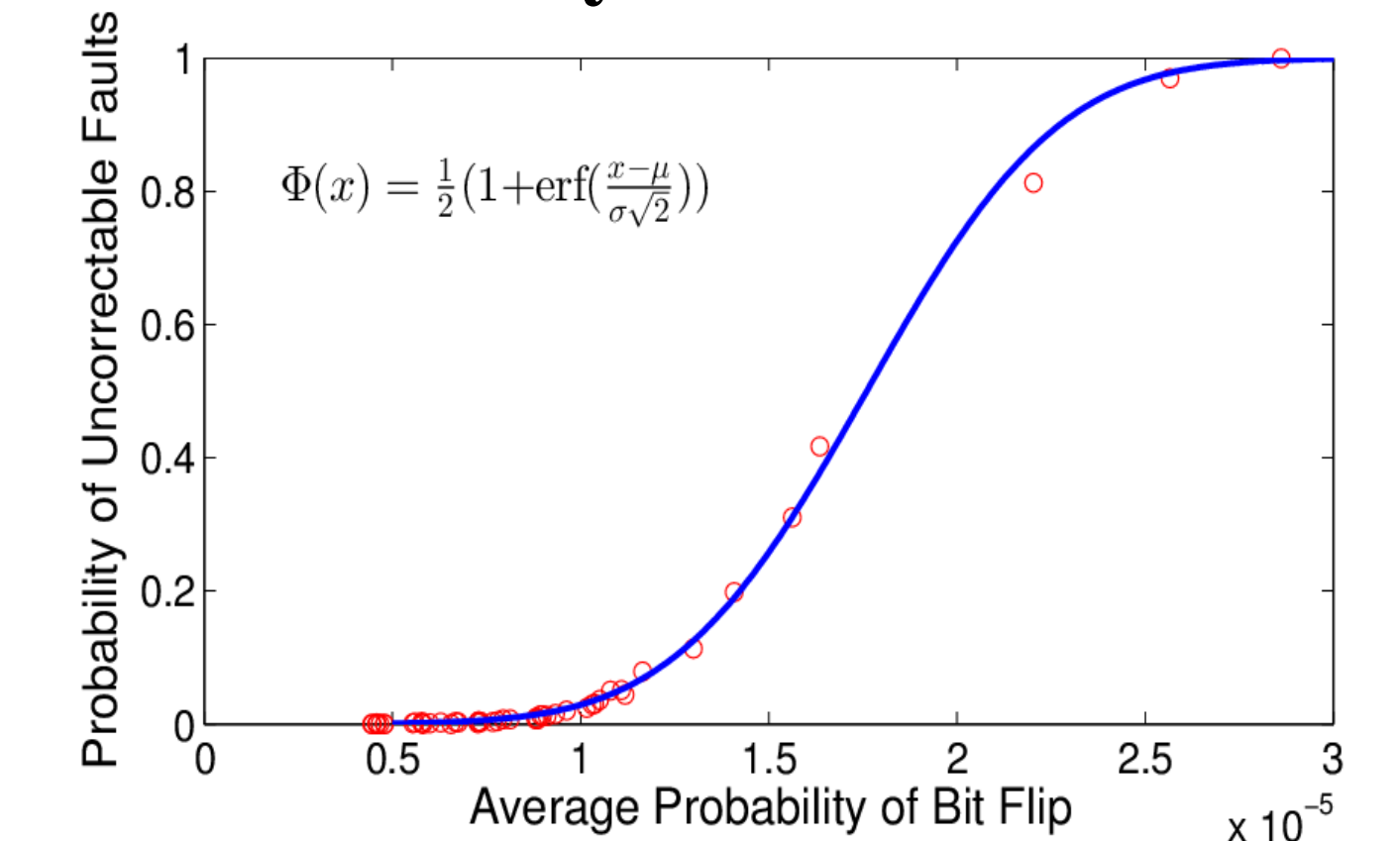


Frequency	Refresh Rate		
	8 ms	12 ms	16 ms
1.5GHz	1.8%	0.0%	0.0%
2.0GHz	1.8%	0.0%	0.0%
2.5GHz	7.2%	0.0%	0.5%
3.0GHz	59.3%	27.5%	2.0%

## Conclusion

- We present a detailed analysis and optimization scheme for 3D CPUs on voltage noise induced DRAM transient fault
- We observe significant correlations between CPU activities and DRAM layer thermal and voltage noise
- We propose a dynamic DRAM management scheme in order to maximize performance while meeting long-term resilience target. Simulation results show that our management scheme achieves 27% increase in performance when comparing to running at the nominal operating point
- The work will be published in ISLEPD 2016

### Converting Bit Error Distribution to Probability of Failure



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